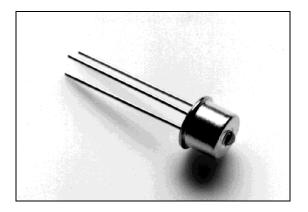
Data Sheet

August 2003



Features

- 780nm Surface-Emitting LED
- 55MHz Bandwidth
- Designed for 62.5/125µm fiber
- Low thermal droop

Applications

- · Baseband Video
- Sensors
- · General Purpose

Ordering Information

MF359 TO-46 Package
MF359 ST ST Housing
MF359 SMA SMA Housing

-40°C to +85°C

Note: Rated Fiber coupled power apply only on the TO-46 package, for housing options fiber coupled power is typically 10% less.

Description

The low thermal droop of this device allows baseband video transmission with minimum distortion. The double-lens optical system provides for optimum coupling of power into the fiber. It matches with the MF446 PIN Photodiode.

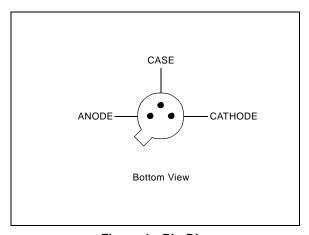


Figure 1 - Pin Diagram

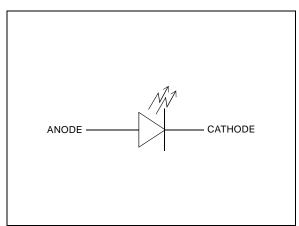


Figure 2 - Functional Schematic

Optical and Electrical Characteristics - Case Temperature 25°C

Parameter	Symbol	Min	Тур	Max	Unit	Test Condition	
Fiber-Coupled Power	P _{fiber}	80	120		μW	I _F =80mA (Note 1)	Fiber:
Rise and Fall Time (10-90%)	t _r ,t _f		6	8	ns	I _F =80mA (no bias)	62.5/ 125μm
Bandwidth (3dB _{el})	f _c		55		MHz	I _F =80mA	Graded
Thermal Droop (non linearity) (Note 2)	ΙΔΡΙ		2		%	I _F =80mA	Index NA=0.275
Peak Wavelength	λ_{p}	760	780	800	nm	I _F =80mA	
Spectral Width (FWHM)	Δλ		50		nm	I _F =80mA	
Forward Voltage (Figure 7)	V _F		2.2	2.6	V	I _F =80mA	
Reverse Current	I _R			20	μΑ	V _R =1V	
Capacitance	С		250		pF	V _R -0V, f=1MHz	7

Note 1: Measured at the exit of 100 meters of fiber.

Note 2: Transient decline in optical power due to self-heating.

Absolute Maximum Ratings

Parameter	Symbol	Limit
Storage Temperature	T _{stg}	-55 to +125°C
Operating Temperature (derating: Figure 6)	T _{op}	-40 to +85°C
Electrical Power Dissipation (derating: Figure 6)	P _{tot}	300 mW
Continuous Forward Current (f<10kHz)	I _F	110 mA
Peak Forward Current (duty cycle<50%,f>1MHz	I _{FRM}	180 mA
Reverse Voltage	V_{R}	1.5 V
Soldering Temperature (2mm from the case for 10 sec.)	T _{sld}	260°C

Thermal Characteristics

Parameter	Symbol	Min	Тур	Max	Unit
Thermal Resistance - Infinite Heat Sink	R _{thjc}			100	°C/W
Thermal Resistance - No Heat Sink	R _{thja}			400	°C/W
Temperature Coefficient - Optical Power	d <i>P</i> /d <i>T</i> _j		-0.5		%/°C
Temperature Coefficient - Wavelength	$\mathrm{d}\lambda/\mathrm{d}T_{\mathrm{j}}$		0.3		nm/°C

Typical Fiber-Coupled Power

Core Diameter/Cladding Diameter Numerical Aperture					
50/125μm	62.5/125μm	100/140μm	200/230μm		
0.20	0.275	0.29	0.37		
60μW	120μW	250μW	400μW		

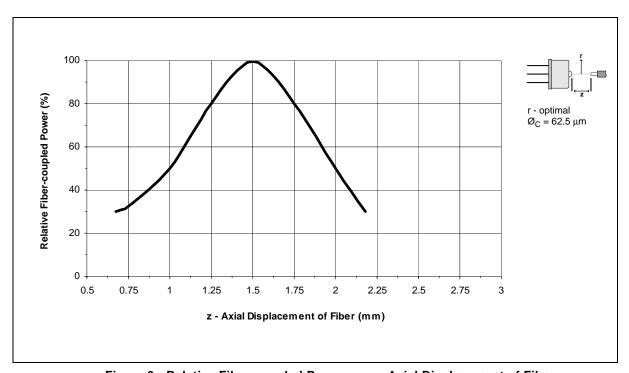


Figure 3 - Relative Fiber-coupled Power vs. z - Axial Displacement of Fiber

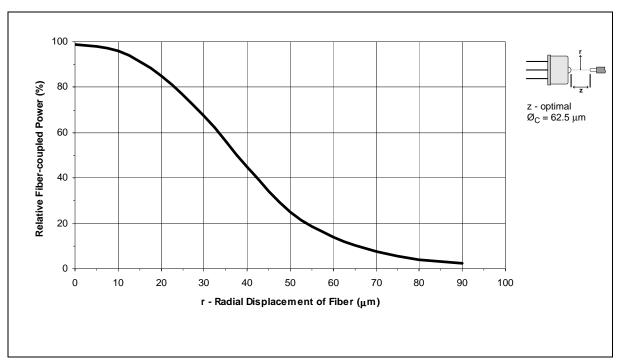


Figure 4 - Relative Fiber-coupled Power vs. r - Radial Displacement of Fiber

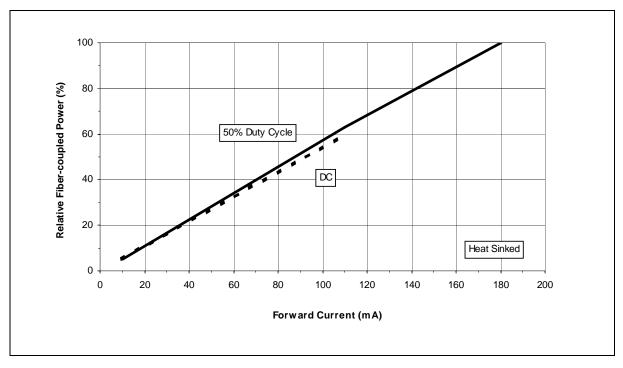


Figure 5 - Relative Fiber-coupled Power vs. Forward Current

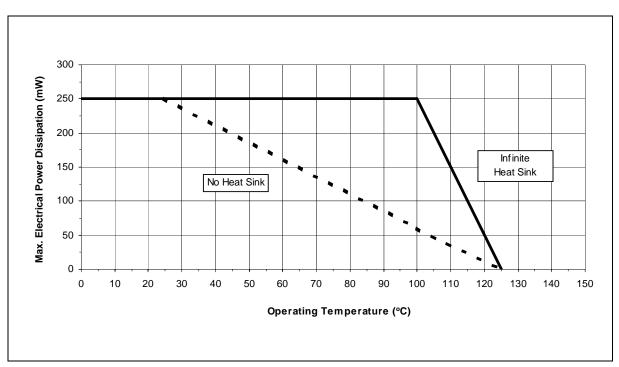


Figure 6 - Max. Electrical Power Dissipation vs. Operating Temperature

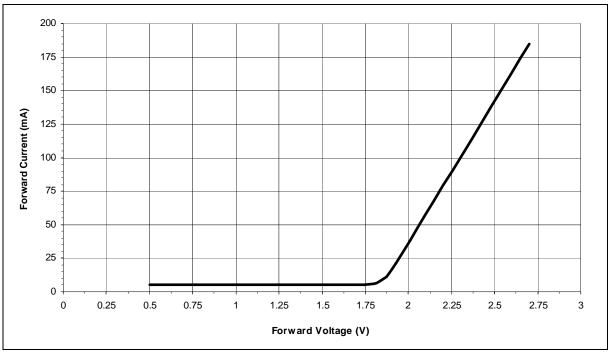
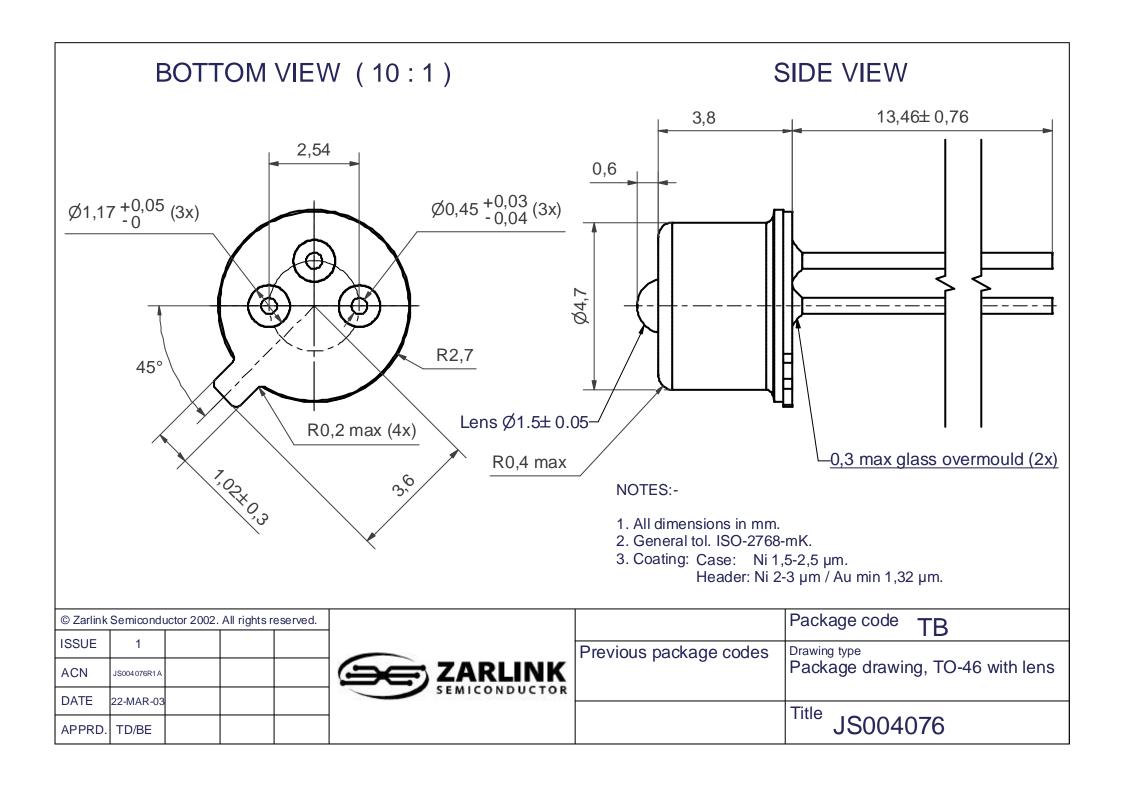


Figure 7 - Forward Current vs. Forward Voltage





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